

Product Change Notification - GBNG-09EAUN458

Date:

16 Jul 2019

Product Category:

Ethernet PHYs

Affected CPNs:

7

Notification subject:

CCB 3473 Final Notice: Qualification of ASE as a new assembly site for selected Micrel KSZ8061 device family available in 48L VQFN (7x7x0.9 mm) package using palladium coated copper with gold flash (CuPdAu) bond wire.

Notification text:

PCN Status:

Final notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of ASE as a new assembly site for selected Micrel KSZ8061 device family available in 48L VQFN (7x7x0.9 mm) package using palladium coated copper with gold flash (CuPdAu) bond wire.

Pre Change:

Assembled at TICP. **Post Change:** Assembled at ASE.

Pre and Post Change Summary:

	Pre Change	Post Change				
Assembly Site	Taiwan IC Packing Corp					
	(TICP)	(ASE)				
Wire material	CuPdAu	CuPdAu				
Die attach material	EN4900	EN4900				
Molding compound material	G631	G631				
Lead frame material	C194	C194				

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve on-time delivery performance by qualifying ASE as a new assembly site.

Change Implementation Status:

In Progress

Estimated First Ship Date:



August 16, 2019 (date code: 1932)

NOTE: Please be advised that after the estimated first ship may receive pre and post change parts.

Time Table Summary:

	August 2018			v	July 2019			August 2019							
Workweek	31	32	33	34	35		27	28	29	30	31	32	33	34	35
Initial PCN Issue Date			Х												
Qual Report									Х						
Availability															
Final PCN Issue Date									Х						
Estimated												Х			
Implementation Date															

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:

August 14, 2018: Issued initial notification.

July 16, 2019: Issued final notification. Attached the qualification report and added estimated first ship date by August 16, 2019.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

PCN_GBNG-09EAUN458_Qual_Report.pdf

Please contact your local <u>Microchip sales office</u> with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

KSZ8061MNGW KSZ8061MNGW-TR